

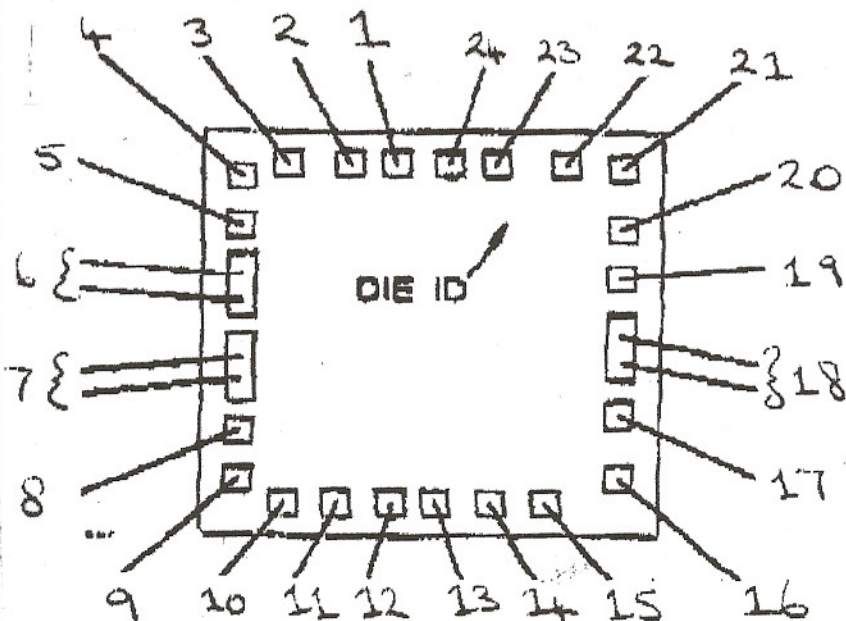


# Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423

Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Pad	Function	Pad	Function
1	D3c	13	D2a
2	D4c	14	D3a
3	D5c	15	D4a
4	Qc	16	D5a
5	Oa	17	D1b
6	VCC	18	VEE
7	VCCA	19	D2b
8	Qb	20	D3b
9	Qb	21	D4b
10	Oa	22	D5b
11	Oa	23	D1c
12	D1a	24	D2c

NOTE: VCCA may be connected to the same bond pad as VCC.

**Topside Metal: Al/12ka thick**

**Backside: Si**

**Backside Potential: -**

**Mask Ref: Z**

**Bond Pads: .004"**

APPROVED BY: CD

MFG: Harris

DIE SIZE: .067" x .066"

THICKNESS: .015"

DATE: 7/25/02

P/N: F1000301